

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (Currently Amended) An electro-optical device comprising:
 - a first substrate;
 - a protection layer formed on a part of the first substrate leaving a region of the first substrate exposed where the protection layer is not formed;
 - ~~a first electrode formed on the protection layer;~~
 - ~~a first inter-substrate conduction unit formed on the protection layer and electrically connected to the first electrode;~~
 - ~~a second substrate opposing the first substrate and having a second electrode formed thereon;~~
 - ~~a second inter-substrate conduction unit formed on the second substrate and electrically connected to the second electrode;~~
 - ~~a conductive member for electrically connecting the first and second inter-substrate units interposed between:~~
 - the protection layer and the first inter-substrate conduction unit, and
 - the second inter-substrate conduction unit, to electrically connect both units together; and
 - a sealant that contains the conductive member bonding the first substrate and the second substrate together by extending on both the protection layer and the exposed region of the first substrate where the protection layer is not formed.

2. (Currently Amended) A device according to Claim 1, wherein the ~~exposed~~ region of the first substrate where the protection layer is not formed extends inboard from an external periphery of the first substrate.

3. (Original) A device according to Claim 1, wherein a shape of the protection layer disposed at a bottom of the first inter-substrate conduction unit is coordinated with a shape of the first inter-substrate conduction unit.

4. (Currently Amended) A device according to Claim 1, wherein:— further comprising a color filter [[is]] formed at a ~~lower layer of the protection layer~~ disposed on the first substrate underneath the protection layer; and

wherein the first substrate is larger than the second substrate so that an extended region of the first substrate is produced when both the substrates are bonded together, and the extended region of the first substrate is provided with a mounting terminal to be connected to the first inter-substrate conduction unit.

5. (Currently Amended) An electro-optical device comprising:

- a first substrate;
- a protection layer formed on a part of the first substrate leaving a region of the first substrate exposed where the protection layer is not formed;
- a first electrode formed on the protection layer on the first substrate;
- a first inter-substrate conduction unit formed on the protection layer and electrically connected to the first electrode;
- a second substrate opposing the first substrate and having a second electrode formed thereon;
- a second inter-substrate conduction unit formed on the second substrate and electrically connected to the second electrode;
- a first wiring pattern formed on the first substrate and electrically connected to the first inter-substrate conduction unit;
- a metallic wiring pattern formed at a lower layer of the protection layer and electrically connected to the first wiring pattern;
- a conductive member for electrically connecting the first and second inter-substrate units interposed between:
 - the protection layer and the first inter-substrate conduction unit, and
 - the second inter-substrate conduction unit, to electrically connect both units together; and
- a sealant that contains the conductive member bonding the first substrate and the second substrate together by extending on both the protection layer and the exposed region of the first substrate where the protection layer is not formed.

6. (Original) A device according to Claim 5, wherein:

a material of the first wiring pattern is the same as a material of the first inter-substrate conduction unit; and

a resistance of the metallic wiring pattern is smaller than a resistance of the first wiring pattern.

7. (Original) A device according to Claim 6, wherein the metallic wiring pattern comprises any one of silver, a silver alloy, aluminum, and an aluminum alloy.

8. (Currently Amended) A device according to Claim 5, wherein the ~~exposed~~ region of the first substrate where the protection layer is not formed extends inboard from an external periphery of the first substrate.

9. (Original) A device according to Claim 5, wherein a shape of the protection layer disposed at a bottom of the first inter-substrate conduction unit is coordinated with a shape of the first inter-substrate conduction unit.

10. (Currently Amended) An electro-optical device comprising:

a first substrate;

a protection layer formed on a part of the first substrate leaving a region of the first substrate exposed where the protection layer is not formed;

~~a first electrode formed on the protection layer;~~

a first inter-substrate conduction unit formed on the protection layer ~~and electrically connected to the first electrode~~;

a second substrate opposing the first substrate ~~and having a second electrode formed thereon~~;

a second inter-substrate conduction unit formed on the second substrate ~~and electrically connected to the second electrode~~;

a conductive member for electrically connecting the first and second inter-substrate units interposed between:

the protection layer and the first inter-substrate conduction unit, and

~~the second inter-substrate conduction unit, to electrically connect both units together;~~ and

a sealant having a first region embracing that contains the conductive member and a second region with a thickness larger than ~~that of the first region, the sealant bonding for embracing the conductive member so as to bond the first substrate and the second substrate together.~~

11. (Original) An electronic instrument comprising an electro-optical device according to claim 1.

12-13. (Cancelled)

14. (New) An electro-optical device comprising;

 a first substrate;

 a protection layer formed on a part of the first substrate leaving a region of the first substrate where the protection layer is not formed, the protection layer having an outer edge defining a plurality of protrusion parts of the protection layer;

 a first inter-substrate conduction unit formed on the protection layer;

 a second substrate opposing the first substrate;

 a second inter-substrate conduction unit formed on the second substrate;

 a conductive member for electrically connecting the first and second inter-substrate units interposed between:

 the protection layer and the first inter-substrate conduction unit, and

 the second inter-substrate conduction unit; and

 a sealant that contains the conductive member bonding the first substrate and the second substrate together by extending on both the protection layer and the region of the first substrate where the protection layer is not formed;

 wherein the region of the first substrate where the protection layer is not formed includes a region between the protrusion parts, and the sealant covers the outer edge of the protection layer and the protrusion parts.